

Abstract

An object of the present invention is to reduce and to stabilize peel strength of a carrier foil in an electrodeposited copper foil with carrier employing an organic adhesive interface, thereby facilitating peeling of the carrier foil. The electrodeposited copper foil with carrier of the present invention contains a carrier foil layer, an organic adhesive interface layer formed on the carrier foil layer, and an electrodeposited copper foil layer formed on the organic adhesive interface layer, wherein the difference between the coefficient of thermal expansion of material forming the carrier foil layer at a certain temperature and that of material forming the electrodeposited copper foil at the same temperature is $4 \times 10^{-7}/\text{deg.C}$ or more.